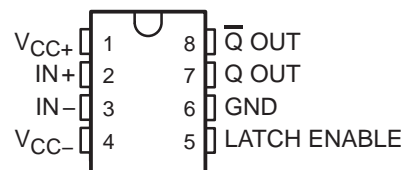


- Ultra-Fast Operation . . . 10 ns (typ)
- Low Positive Supply Current  
12.7 mA (Typ)
- Operates From a Single 5-V Supply or From a Split  $\pm 5$ -V Supply
- Complementary Outputs
- Input Common-Mode Voltage Includes Negative Rail
- Low Offset Voltage
- No Minimum Slew Rate Requirement
- Output Latch Capability
- Functional Replacement to the LT1116

D AND PW PACKAGE  
(TOP VIEW)

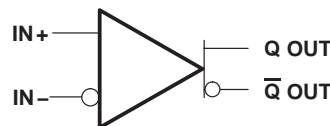


**description**

The TL3116 is an ultra-fast comparator designed to interface directly to TTL logic while operating from either a single 5-V power supply or dual  $\pm 5$ -V supplies. The input common-mode voltage extends to the negative rail for ground sensing applications. It features extremely tight offset voltage and high gain for precision applications. It has complementary outputs that can be latched using the LATCH ENABLE terminal. Figure 1 shows the positive supply current of the comparator. The TL3116 only requires 12.7 mA (typical) to achieve a propagation delay of 10 ns.

The TL3116 is a pin-for-pin functional replacement for the LT1116 comparator, offering high-speed operation but consuming much less power.

symbol (each comparator)



**POSITIVE SUPPLY CURRENT**  
**vs**  
**FREE-AIR TEMPERATURE**

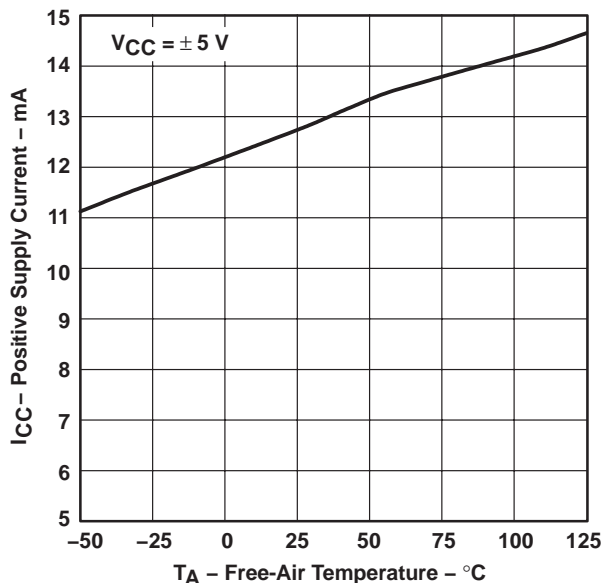


Figure 1

AVAILABLE OPTIONS

T <sub>A</sub>	PACKAGED DEVICES		CHIP FORM <sup>‡</sup> (Y)
	SMALL OUTLINE <sup>†</sup> (D)	TSSOP (PW)	
0°C to 70°C	TL3116CD	TL3116CPWLE	TL3116Y
-40°C to 85°C	TL3116ID	TL3116IPWLE	—

<sup>†</sup> The PW packages are available left-ended taped and reeled only.

<sup>‡</sup> Chip forms are tested at T<sub>A</sub> = 25°C only.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

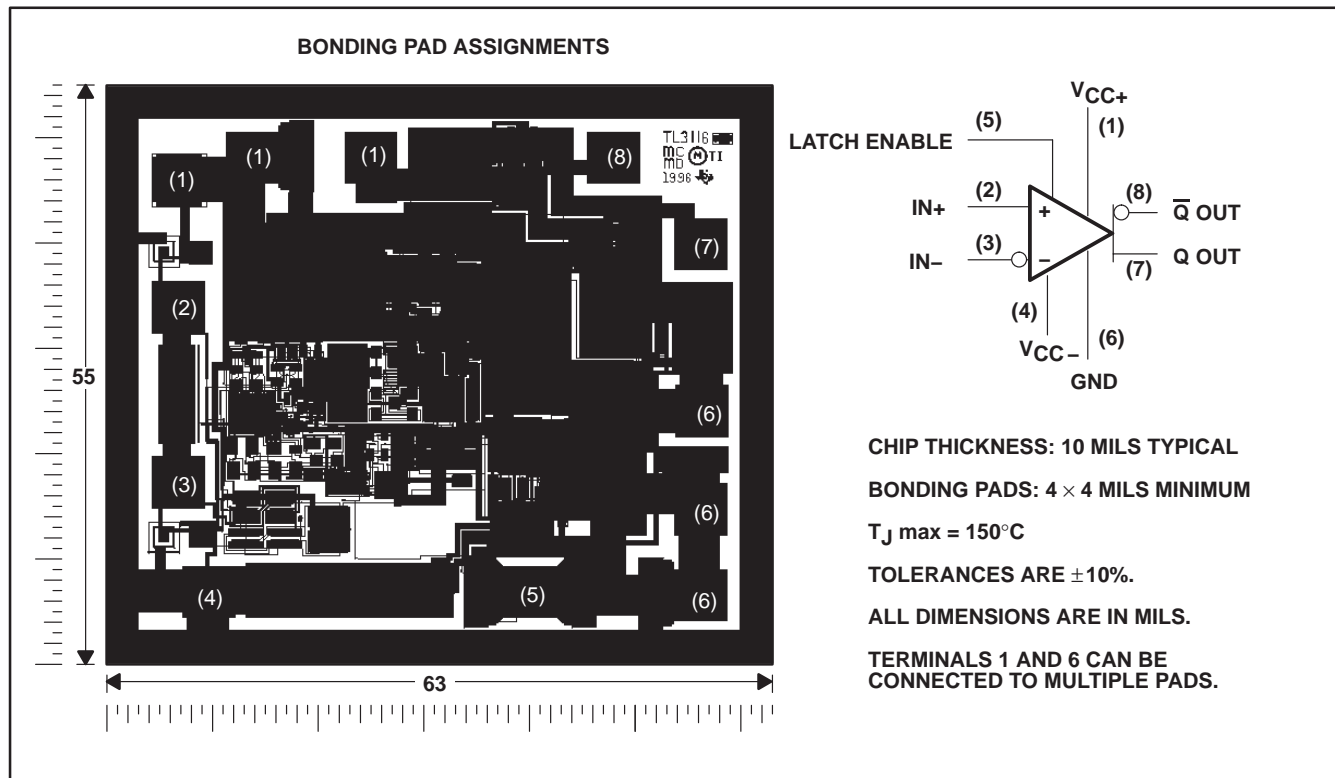


# TL3116, TL3116Y ULTRA-FAST LOW-POWER PRECISION COMPARATORS

SLCS132C – MARCH 1997 – REVISED MAY 1997

## TL3116Y chip information

This chip, when properly assembled, displays characteristics similar to the TL3116C. Thermal compression or ultrasonic bonding may be used on the doped-aluminum bonding pads. Chips may be mounted with conductive epoxy or a gold-silicon preform.



COMPONENT COUNT	
Bipolars	53
MOSFETs	49
Resistors	46
Capacitors	14

**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage, $V_{DD}$ (see Note 1)	– 7 V to 7 V
Differential input voltage, $V_{ID}$ (see Note 2)	7 V
Input voltage range, $V_I$	7 V
Input voltage, $V_I$ (LATCH ENABLE)	7 V
Output current, $I_O$	$\pm 20$ mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, $T_A$	–40°C to 85°C
Storage temperature range, $T_{stg}$	– 65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to network ground.  
 2. Differential voltages are at IN+ with respect to IN–.

**DISSIPATION RATING TABLE**

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING
D	725 mW	5.8 mW/°C	464 mW
PW	525 mW	4.2 mW/°C	336 mW

**TL3116, TL3116Y**  
**ULTRA-FAST LOW-POWER**  
**PRECISION COMPARATORS**

SLCS132C – MARCH 1997 – REVISED MAY 1997

electrical characteristics at specified operating free-air temperature,  $V_{DD} = \pm 5\text{ V}$ ,  $V_{LE} = 0$  (unless otherwise noted)

PARAMETER		TEST CONDITION†	TL3116C			TL3116I			UNIT
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
$V_{IO}$	Input offset voltage	$T_A = 25^\circ\text{C}$		0.5	3		0.5	3	mV
		$T_A = \text{full range}$			3.5			3.5	
$\alpha_{VIO}$	Temperature coefficient of input offset voltage			-2.5			-2.8	$\mu\text{V}/^\circ\text{C}$	
$I_{IO}$	Input offset current	$T_A = 25^\circ\text{C}$		0.1	0.2		0.1	0.2	$\mu\text{A}$
		$T_A = \text{full range}$			0.3			0.35	
$I_{IB}$	Input bias current	$T_A = 25^\circ\text{C}$		0.7	1.1		0.7	1.1	$\mu\text{A}$
		$T_A = \text{full range}$			1.2			1.5	
$V_{ICR}$	Common-mode input voltage range	$V_{DD} = \pm 5\text{ V}$	-5		2.5	-5		2.5	V
		$V_{DD} = 5\text{ V}$	0		2.5	0		2.5	
CMRR	Common-mode rejection ratio	$-5 \leq V_{IC} \leq 2.5\text{ V}$	75	100		75	100	dB	
$k_{SVR}$	Supply-voltage rejection ratio	Positive supply: $4.6\text{ V} \leq +V_{DD} \leq 5.4\text{ V}$ , $T_A = 25^\circ\text{C}$	60	80		60	80	dB	
		Negative supply: $-7\text{ V} \leq -V_{DD} \leq -2\text{ V}$ , $T_A = 25^\circ\text{C}$	80	100		80	100		
$V_{OL}$	Low-level output voltage	$I_{(\text{sink})} = 4\text{ mA}$ , $T_A = 25^\circ\text{C}$ , $V_+ \leq 4.6\text{ V}$		400	600		400	600	mV
		$I_{(\text{sink})} = 10\text{ mA}$ , $T_A = 25^\circ\text{C}$ , $V_+ \leq 4.6\text{ V}$		750			750		
$V_{OH}$	High-level output voltage	$V_+ \leq 4.6\text{ V}$ , $T_A = 25^\circ\text{C}$ , $I_O = 1\text{ mA}$	3.6	3.9		3.6	3.9	V	
		$V_+ \leq 4.6\text{ V}$ , $T_A = 25^\circ\text{C}$ , $I_O = 10\text{ mA}$	3.4	3.8		3.4	3.8		
$I_{CC}$	Positive supply current	$T_A = \text{full range}$		12.7	14.7		12.7	15	mA
	Negative supply current			-2.6			-3		
$V_{IL}$	Low-level input voltage (LATCH ENABLE)			0.8			0.8	V	
$V_{IH}$	High-level input voltage (LATCH ENABLE)		2			2		V	
$I_{IL}$	Low-level input current (LATCH ENABLE)	$V_{LE} = 0$		0	1		0	1	$\mu\text{A}$
		$V_{LE} = 2\text{ V}$		24	39		24	45	$\mu\text{A}$

† Full range for the TL3116C is  $T_A = 0^\circ\text{C}$  to  $70^\circ\text{C}$ . Full range for the TL3116I is  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$ .

‡ All typical values are measures with  $T_A = 25^\circ\text{C}$ .



**switching characteristics,  $V_{DD} = \pm 5\text{ V}$ ,  $V_{LE} = 0$**

PARAMETER	TEST CONDITION†		TL3116C			TL3116I			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
$t_{pd1}$ Propagation delay time‡	$\Delta V_I = 100\text{ mV}$ , $V_{OD} = 5\text{ mV}$	$T_A = 25^\circ\text{C}$	9.9	12		9.9	12	ns	
		$T_A = \text{full range}$	9.9	14		9.9	15		
	$\Delta V_I = 100\text{ mV}$ , $V_{OD} = 20\text{ mV}$	$T_A = 25^\circ\text{C}$	8.2	10.3		8.2	10.3		
		$T_A = \text{full range}$	8.2	12.7		8.2	13.7		
$t_{sk(p)}$ Pulse skew ( $t_{pd+} - t_{pd-}$ )	$\Delta V_I = 100\text{ mV}$ , $T_A = 25^\circ\text{C}$	$V_{OD} = 5\text{ mV}$	0.5			0.5	ns		
$t_{su}$ Setup time, LATCH ENABLE			3.4			3.4	ns		

† Full range for the TL3116C is  $0^\circ\text{C}$  to  $70^\circ\text{C}$ . Full range for the TL3116I is  $-40^\circ\text{C}$  to  $85^\circ\text{C}$ .

‡  $t_{pd1}$  cannot be measured in automatic handling equipment with low values of overdrive. The TL3116 is 100% tested with a 1-V step and 500-mV overdrive at  $T_A = 25^\circ\text{C}$  only. Correlation tests have shown that  $t_{pd1}$  limits given can be ensured with this test, if additional dc tests are performed to ensure that all internal bias conditions are correct. For low overdrive conditions,  $V_{OS}$  is added to the overdrive.

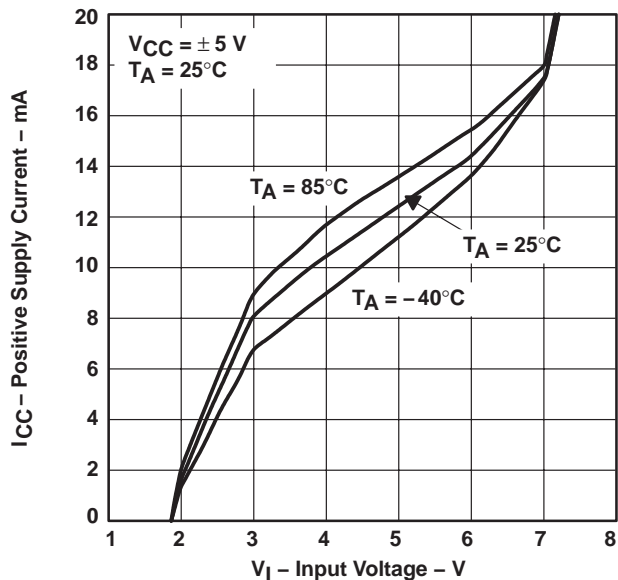
**TYPICAL CHARACTERISTICS**

**Table of Graphs**

		FIGURE	
$I_{CC}$	Positive supply current	vs Input voltage	2
		vs Frequency	3
		vs Free-air temperature	4
$I_{CC}$	Negative supply current	vs Free-air temperature	5
$t_{pd}$	Propagation delay time	vs Overdrive voltage	6
		vs Supply voltage	7
		vs Input impedance	8
		vs Load capacitance	9
		vs Free-air temperature	10
$V_{IC}$	Common-mode input voltage	vs Free-air temperature	11
$V_{IT}$	Input threshold voltage (LATCH ENABLE)	vs Free-air temperature	12
$V_O$	Output voltage	vs Output source current	13
		vs Output sink current	14
$I_I$	Input current (LATCH ENABLE)	vs Input voltage	15

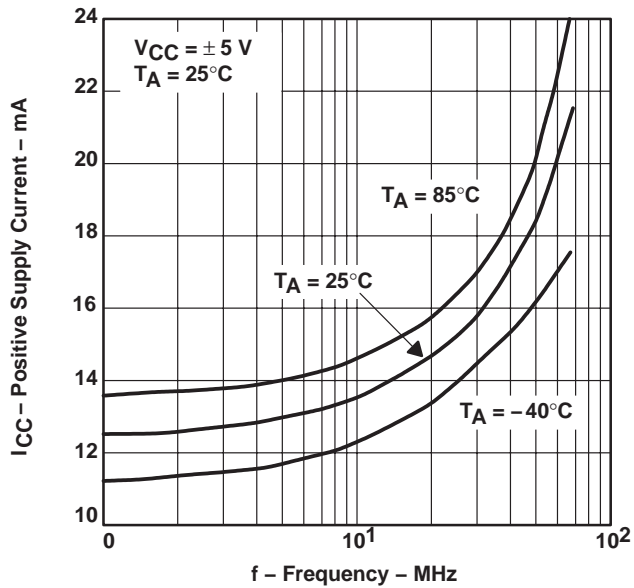
**TYPICAL CHARACTERISTICS**

**POSITIVE SUPPLY CURRENT  
 vs  
 INPUT VOLTAGE**



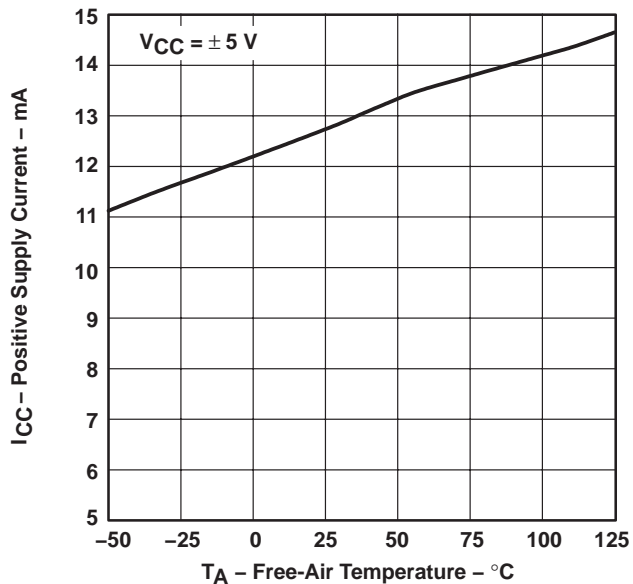
**Figure 2**

**POSITIVE SUPPLY CURRENT  
 vs  
 FREQUENCY**



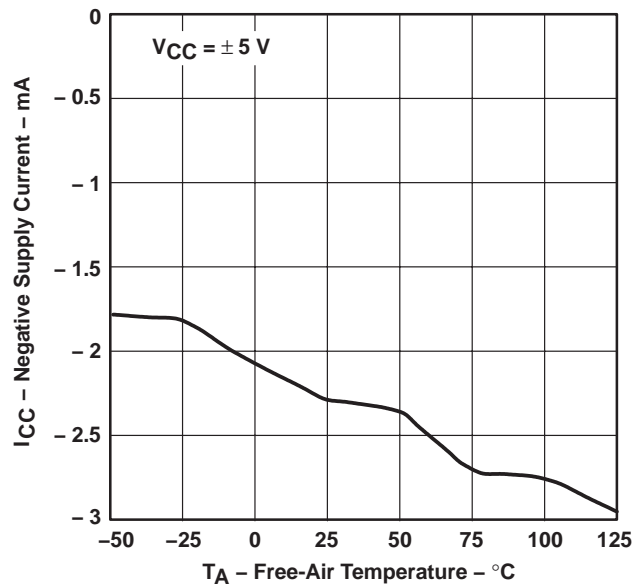
**Figure 3**

**POSITIVE SUPPLY CURRENT  
 vs  
 FREE-AIR TEMPERATURE**



**Figure 4**

**NEGATIVE SUPPLY CURRENT  
 vs  
 FREE-AIR TEMPERATURE**



**Figure 5**

TYPICAL CHARACTERISTICS

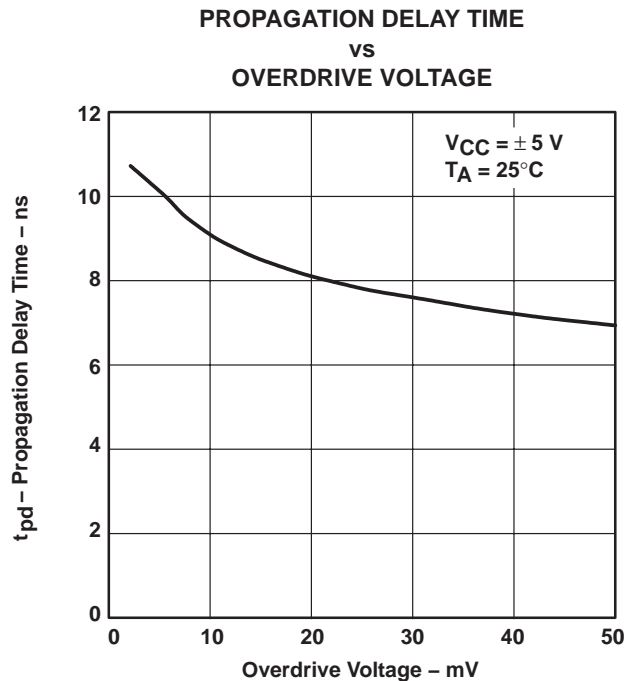


Figure 6

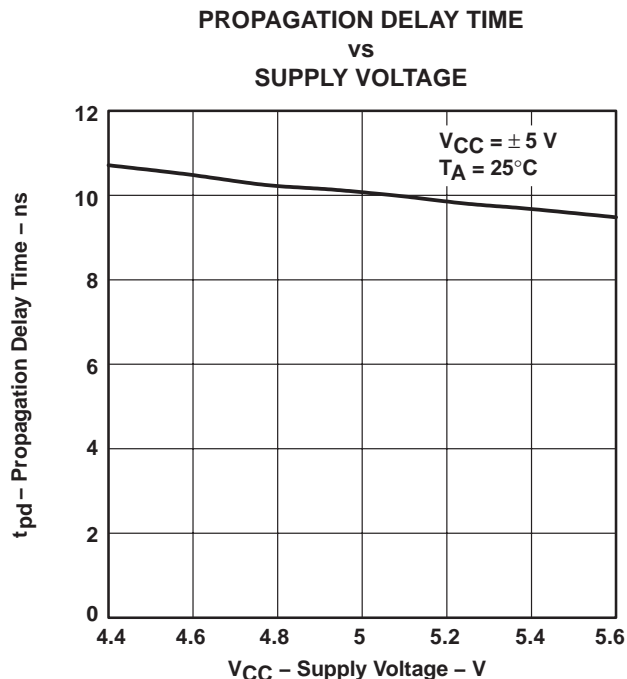


Figure 7

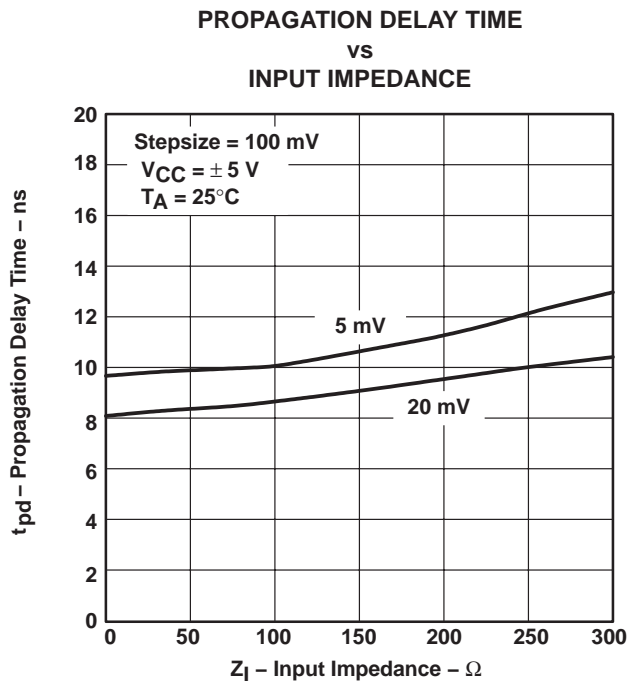


Figure 8

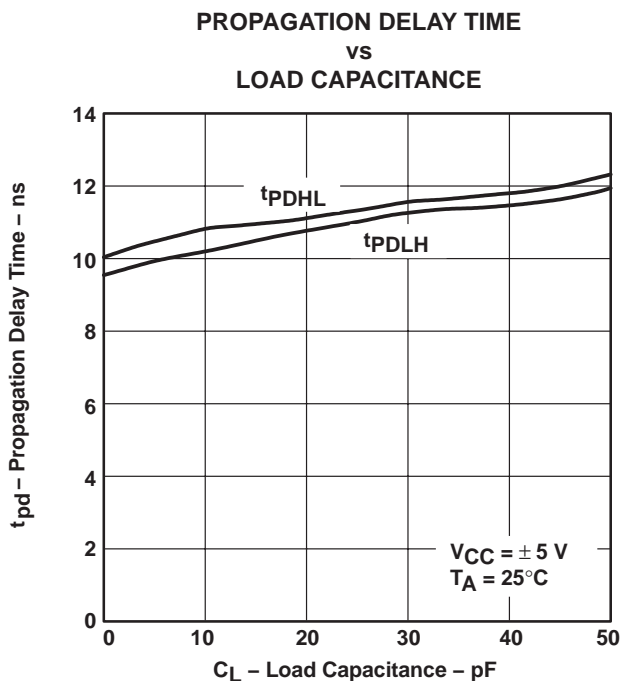
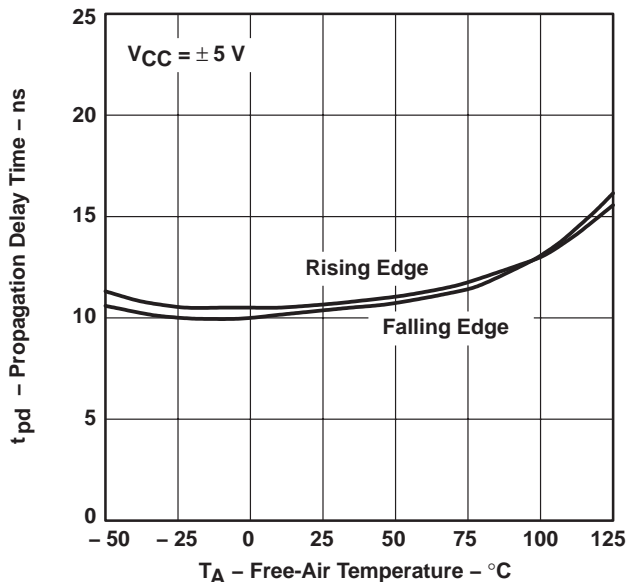


Figure 9

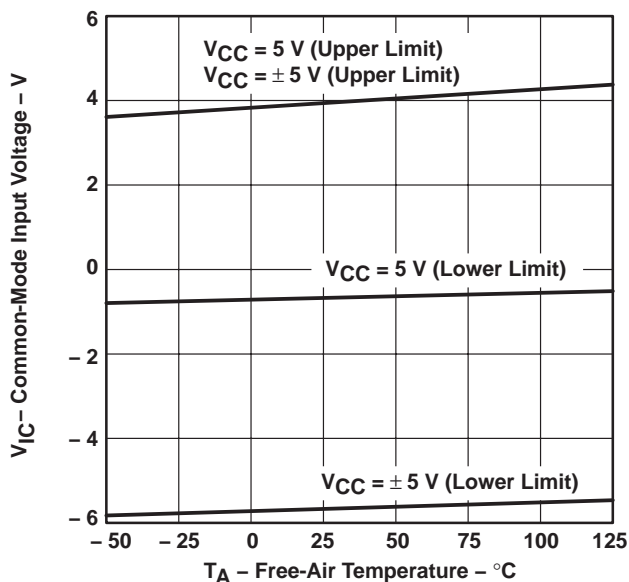
**TYPICAL CHARACTERISTICS**

**PROPAGATION DELAY TIME**  
 vs  
**FREE-AIR TEMPERATURE**



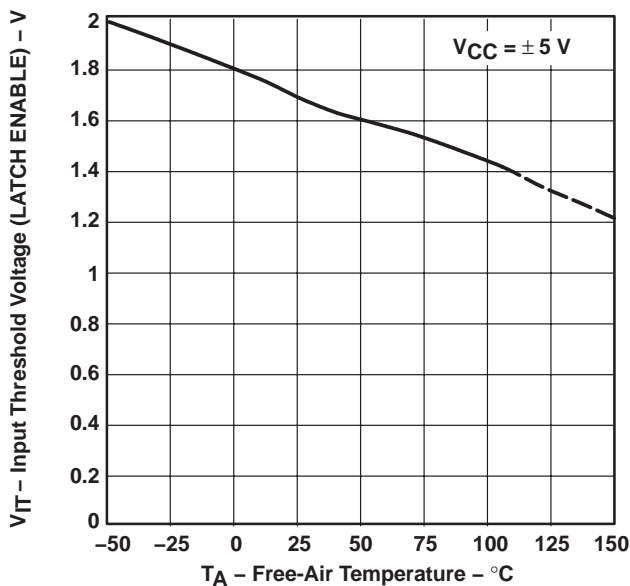
**Figure 10**

**COMMON-MODE INPUT VOLTAGE**  
 vs  
**FREE-AIR TEMPERATURE**



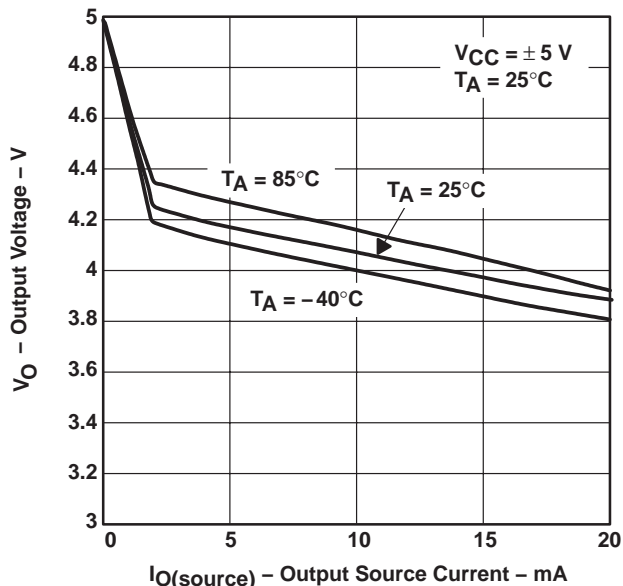
**Figure 11**

**INPUT THRESHOLD VOLTAGE (LATCH ENABLE)**  
 vs  
**FREE-AIR TEMPERATURE**



**Figure 12**

**OUTPUT VOLTAGE**  
 vs  
**OUTPUT SOURCE CURRENT**



**Figure 13**



TYPICAL CHARACTERISTICS

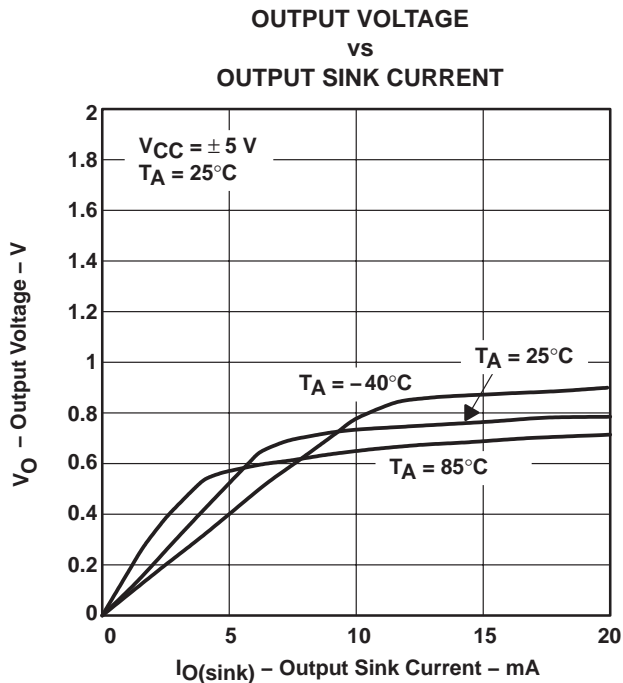


Figure 14

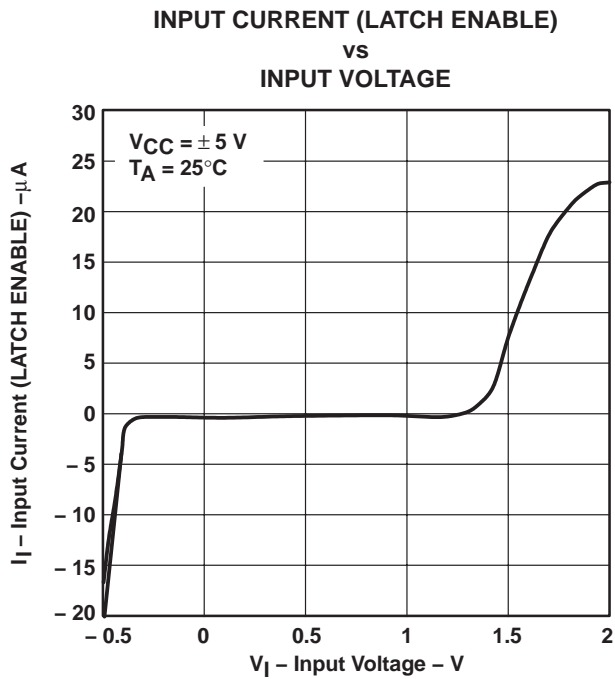


Figure 15

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL3116CDR	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	0 to 70	3116C	
TL3116CPWR	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI	0 to 70	T3116	
TL3116ID	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-40 to 85	3116I	
TL3116IDR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	3116I	Samples
TL3116IPWR	ACTIVE	TSSOP	PW	8	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3116	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL3116IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3116IPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL3116IDR	SOIC	D	8	2500	350.0	350.0	43.0
TL3116IPWR	TSSOP	PW	8	2000	356.0	356.0	35.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TL3116CD	D	SOIC	8	75	505.46	6.76	3810	4



D0008A

# PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

# EXAMPLE BOARD LAYOUT

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON .005 INCH [0.125 MM] THICK STENCIL  
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

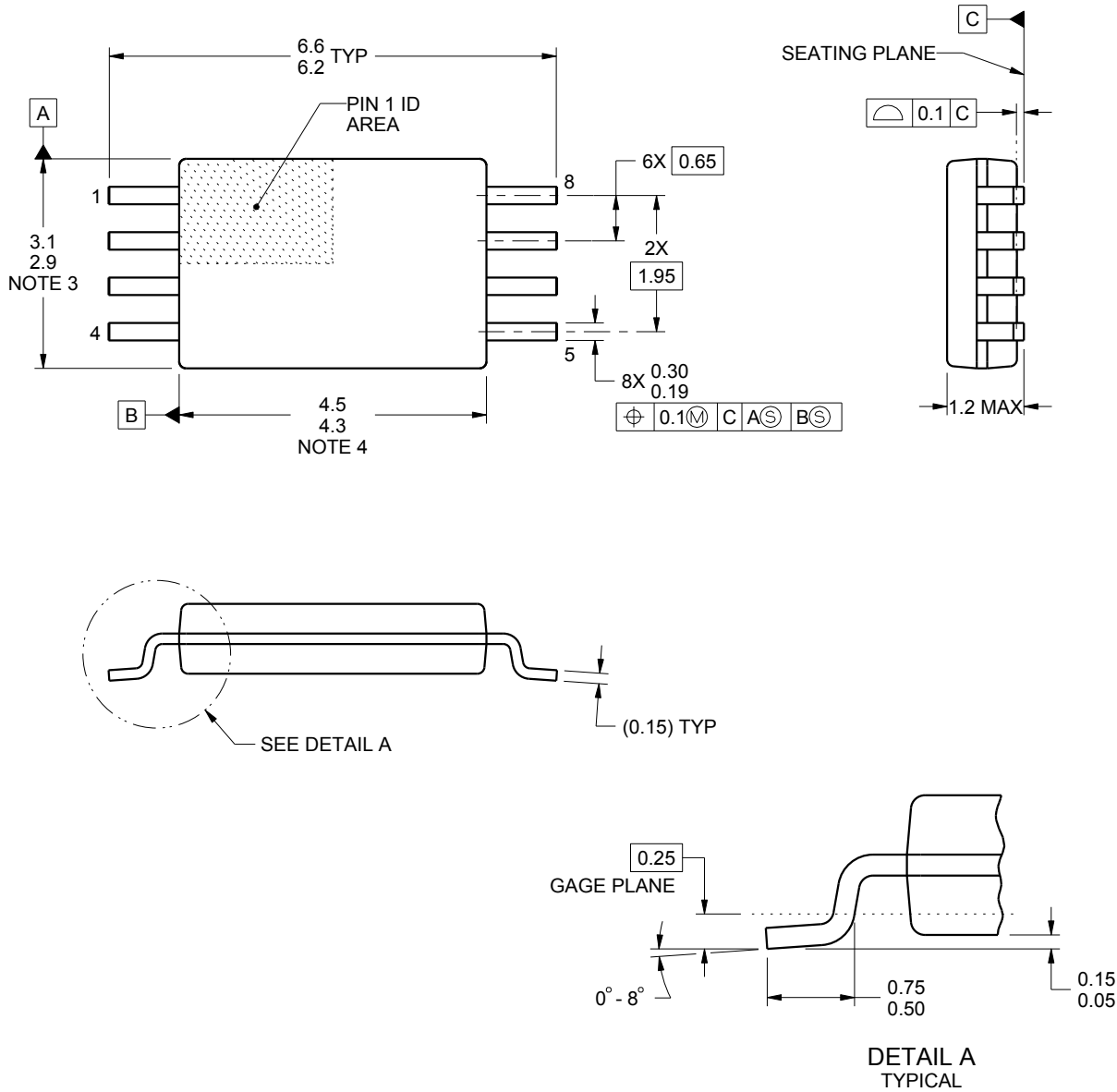
PW0008A



# PACKAGE OUTLINE

## TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4221848/A 02/2015

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.

# EXAMPLE BOARD LAYOUT

PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:10X



SOLDER MASK DETAILS  
NOT TO SCALE

4221848/A 02/2015

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:10X

4221848/A 02/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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